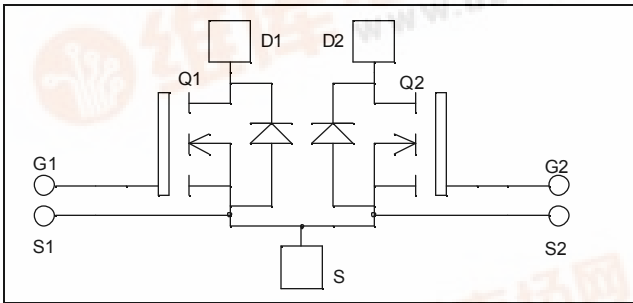




APT50DUM19G

**Dual common source
MOSFET Power Module**

**$V_{DSS} = 500V$
 $R_{DSon} = 19m\Omega$ typ @ $T_j = 25^\circ C$
 $I_D = 163A$ @ $T_c = 25^\circ C$**



Application

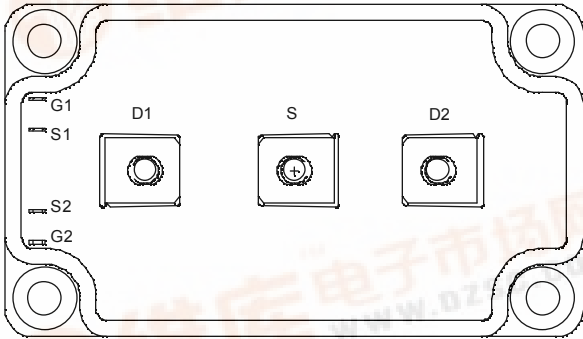
- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	500	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	163
		$T_c = 80^\circ C$	122
I_{DM}	Pulsed Drain current	652	A
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	22.5	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	1136
I_{AR}	Avalanche current (repetitive and non repetitive)	46	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	2500	



All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 500V$	$T_j = 25^\circ\text{C}$			200	μA
		$V_{GS} = 0V, V_{DS} = 400V$	$T_j = 125^\circ\text{C}$			1000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 81.5A$		19	22.5	$\text{m}\Omega$	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{mA}$	3		5	V	
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 200	nA	

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		22.4		nF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		4.8		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		0.36		
Q_g	Total gate Charge	$V_{GS} = 10V$		492		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 250V$		132		
Q_{gd}	Gate – Drain Charge	$I_D = 163A$		260		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 333V$ $I_D = 163A$ $R_G = 1\Omega$		18		ns
T_r	Rise Time			35		
$T_{d(off)}$	Turn-off Delay Time			87		
T_f	Fall Time			77		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 333V$ $I_D = 163A, R_G = 1\Omega$		3020		μJ
E_{off}	Turn-off Switching Energy			2904		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 333V$ $I_D = 163A, R_G = 1\Omega$		4964		μJ
E_{off}	Turn-off Switching Energy			3384		

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I_S	Continuous Source current (Body diode)		$T_c = 25^\circ\text{C}$			163	A
			$T_c = 80^\circ\text{C}$			122	
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -163A$			1.3	V	
dv/dt	Peak Diode Recovery ①				8	V/ns	
t_{rr}	Reverse Recovery Time	$I_S = -163A, V_R = 250V$		680		ns	
Q_{rr}	Reverse Recovery Charge	$di_s/dt = 400A/\mu\text{s}$		57		μC	

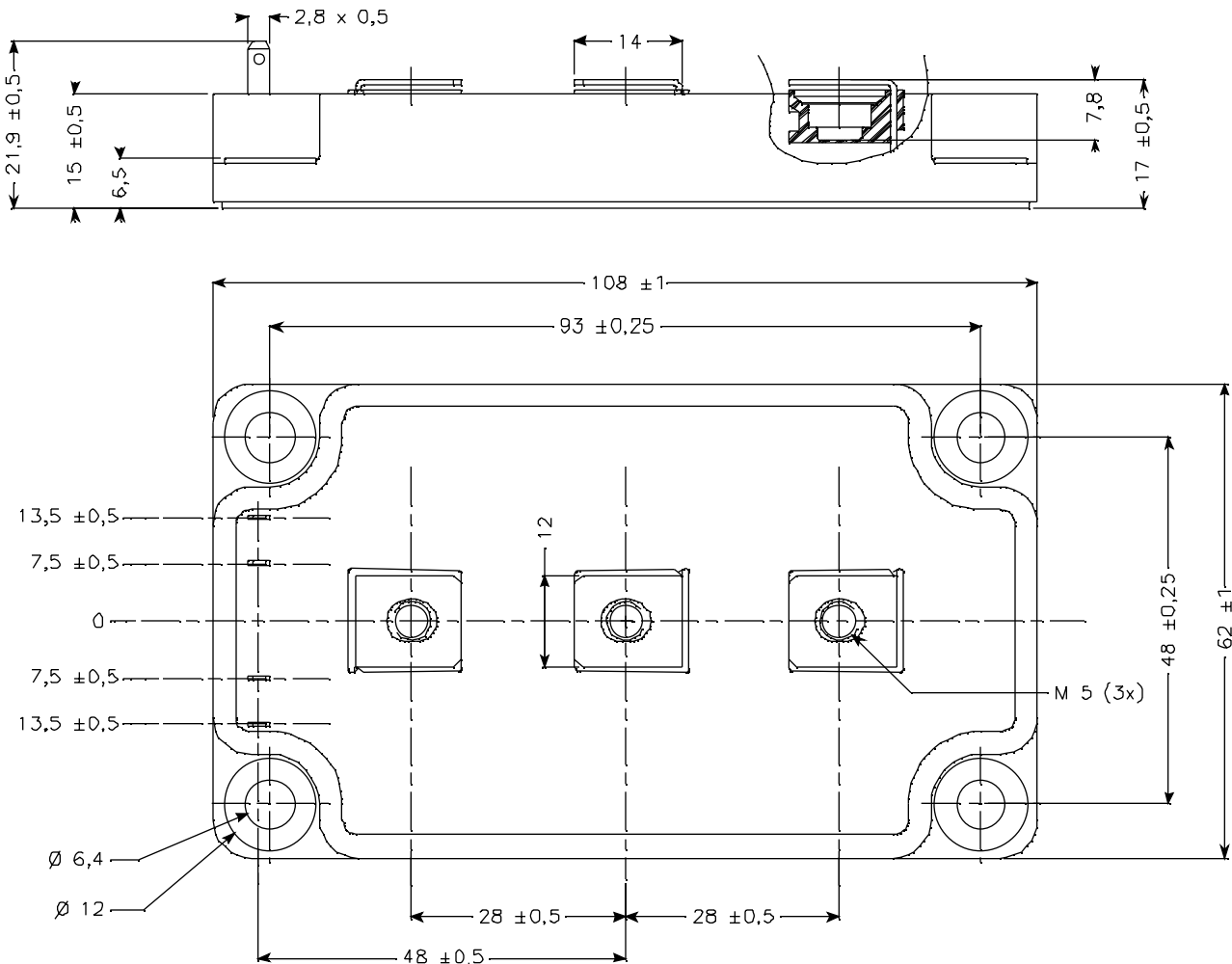
 ① dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$$I_S \leq -163A \quad di/dt \leq 700A/\mu\text{s} \quad V_R \leq V_{DSS} \quad T_j \leq 150^\circ\text{C}$$

Thermal and package characteristics

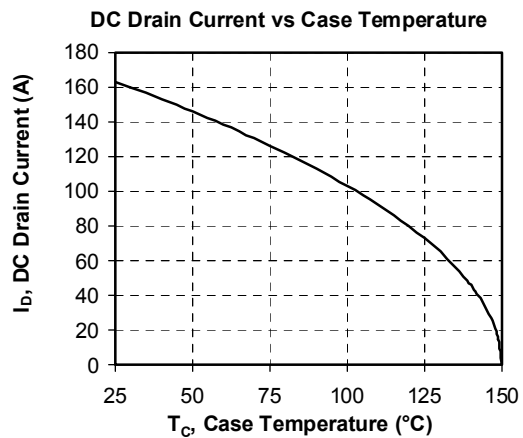
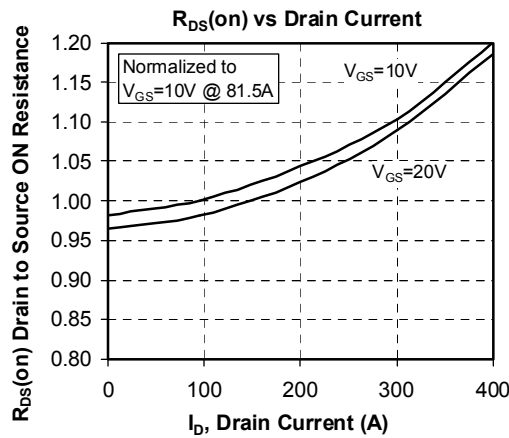
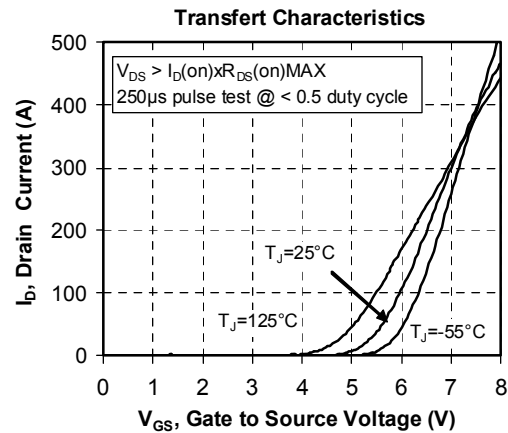
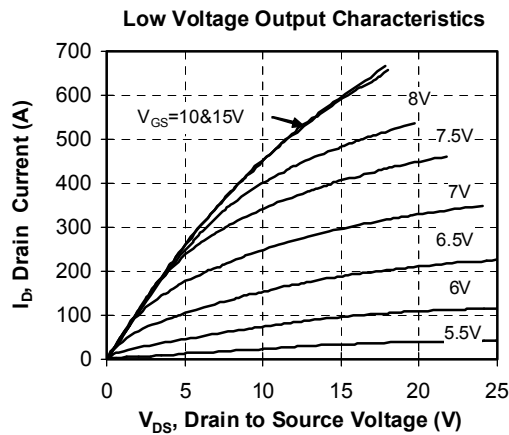
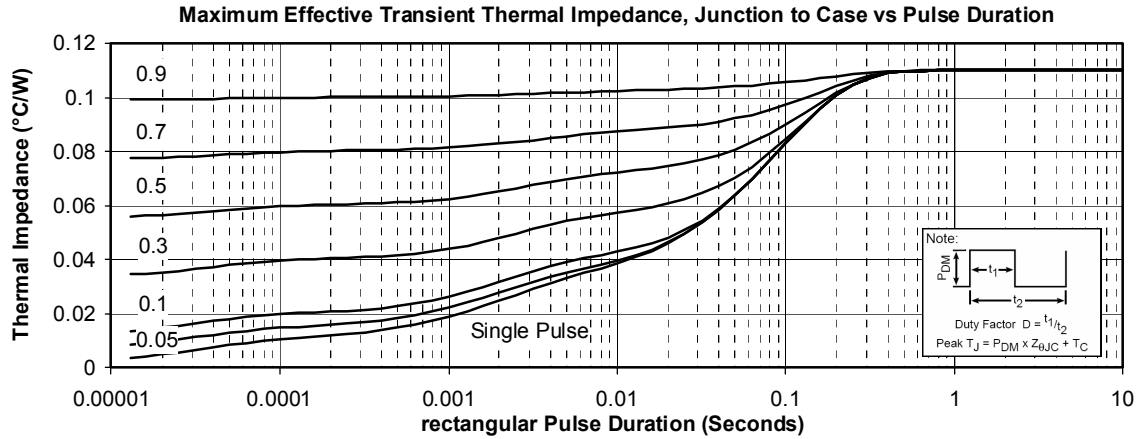
Symbol	Characteristic	Min	Typ	Max	Unit	
R_{thJC}	Junction to Case Thermal Resistance			0.11	°C/W	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I isol < 1mA, 50/60Hz	2500			V	
T_J	Operating junction temperature range	-40		150	°C	
T_{STG}	Storage Temperature Range	-40		125		
T_C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight			280	g	

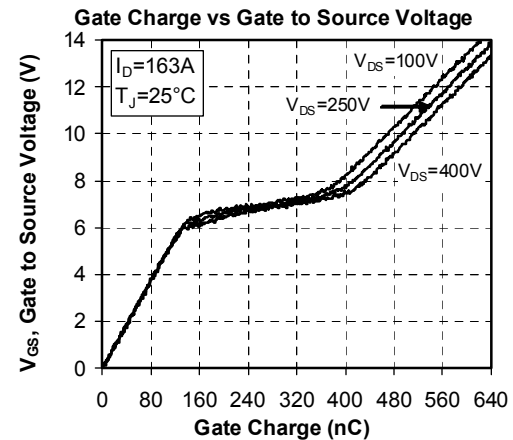
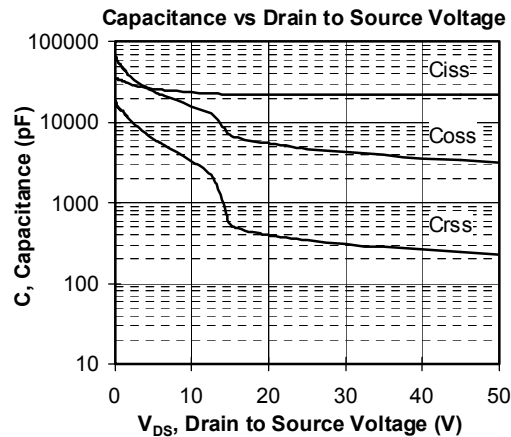
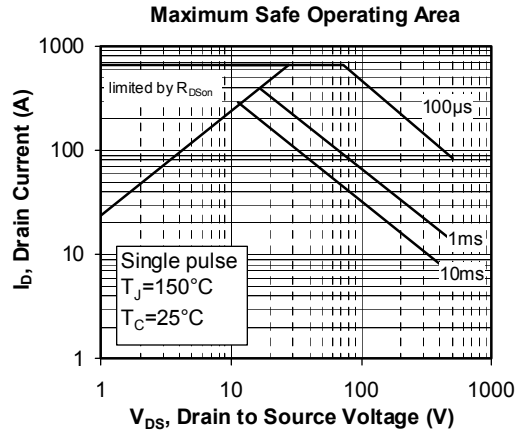
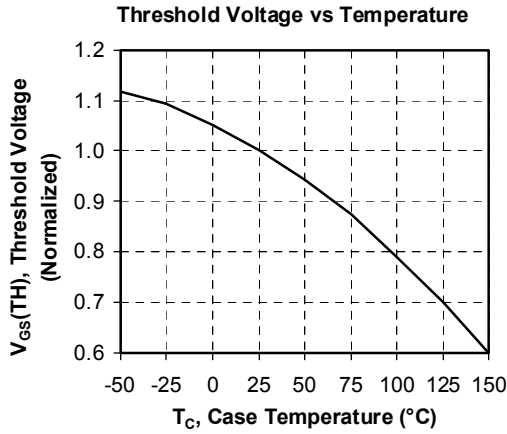
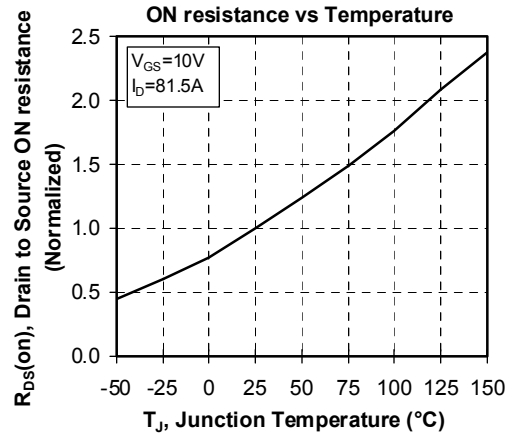
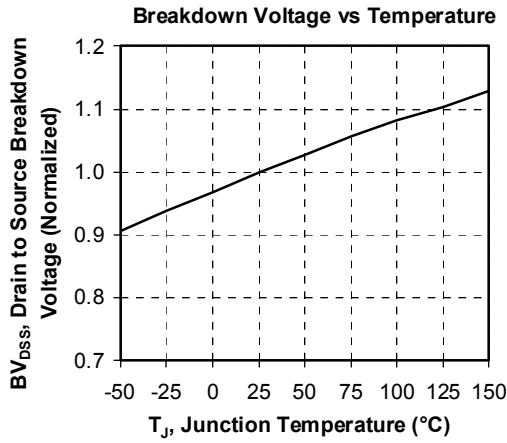
SP6 Package outline (dimensions in mm)

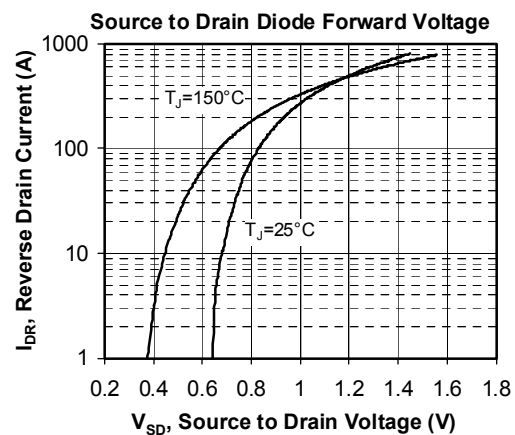
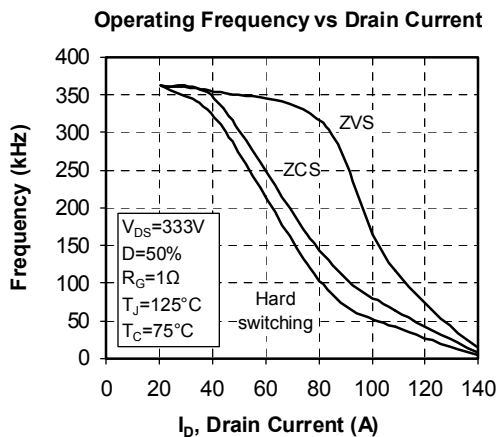
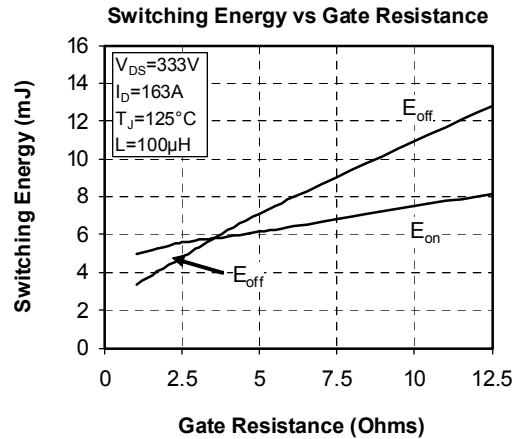
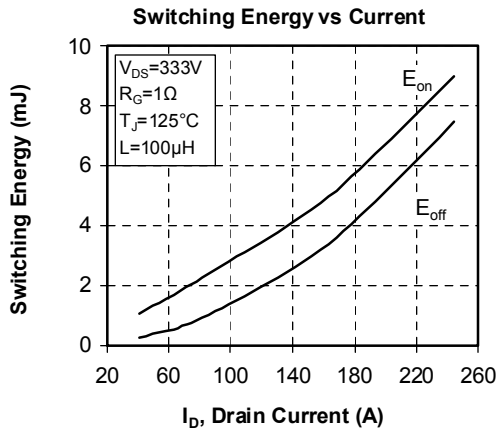
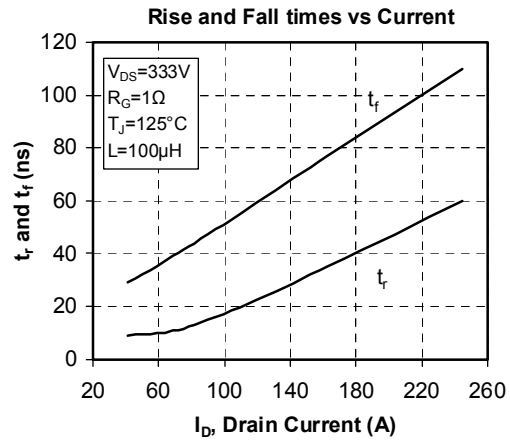
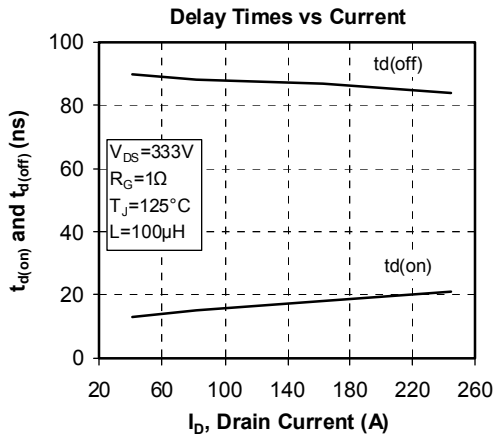


See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve







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